

**PATENT ASSIGNMENT**

Electronic Version v1.1  
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
Harutaka Adachi	03/05/2009
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Shoichi Amano	03/05/2009
Takashi Sawai	03/05/2009
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<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	12406376
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OP \$40.00 12406376

Total Attachments: 2  
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A S S I G N M E N T

In consideration of value received, I, having a mailing address at c/o Intellectual Property Support Department, OLYMPUS INTELLECTUAL PROPERTY SERVICES CO., LTD., 2-3 Kuboyama-cho, Hachioji-shi, Tokyo 192-8512, Japan, and a residence as stated below next to my name, the sole inventor (if only one name is listed below) or a joint inventor (if plural inventors are listed below) of an invention described in an application for United States patent entitled:

ELECTRIC BENDING ENDOSCOPE

said application having been filed on  
and assigned Application No. ;  
sell and assign to  
OLYMPUS MEDICAL SYSTEMS CORP.  
a corporation of Japan, having a business address at  
43-2, Hatagaya 2-chome, Shibuya-ku, Tokyo 151-0072 Japan

its successors, assigns or nominees, hereinafter referred to as "Assignee", my entire right, title and interest in and to said invention as disclosed, shown and described in said application for United States patent : (check one)

- [X] executed concurrently herewith;  
 [ ] executed separately herefrom;

and in and to all applications for patent and patents for said invention including all divisions, reissues, continuations, substitutions and extensions thereof and all rights arising under or pursuant to any and all international agreements, treaties or laws relating to the protection of industrial property, including rights of priority, resulting from the filing of any of said applications; and I authorize and request any official whose duty is to issue patents, to issue any patent on said invention or resulting therefrom to said Assignee, and I agree that on request and without further consideration, but at the expense of said Assignee, I will communicate to said Assignee or its representatives all facts known to me respecting said invention and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing, reissue or other applications, make all rightful oaths and declarations, and generally do everything possible to aid said Assignee to obtain and enforce proper patent protection for said invention in all countries.

I hereby grant the following law firm the power to insert on this Assignment any further identification which may be necessary or desirable in order to comply with the Rules of the U.S. Patent and Trademark Office for recordation of this document.

Ostrolenk, Faber Gerb & Soffen, LLP, 1180 Avenue of the Americas New York, N.Y. 10036-8403

ASSIGNMENT

<u>Inventor: (Signature)</u>	<u>Date</u>	<u>Residence</u>
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